

B2887 Board Size (mm)



B2887 BOARD SPECIFICATIONS

1. Board Layers: 8
2. Layer Stack Order:
 Layer1 (Artwork_1): Top Signal_2, 0.5 oz, diff. 100 ohms
 Layer2 (Artwork_2): Power_1, P5V, 1 oz
 Layer3 (Artwork_3): Power_2, Ground, 1 oz
 Layer4 (Artwork_4): Bot Signal_2, 0.5 oz, diff 100 ohms
3. Apply silkscreen on both side:
 Artwork_5: Top silkscreen.
 Artwork_6: Bot silkscreen.
4. Apply solder mask over bare copper on both side:
 Artwork_7: Top solder mask
 Artwork_8: Bottom solde mask
5. Material: FR4
6. Board thickness: 0.062'' +/- 0.010.
7. TRACE IMPEDENCE: diff 100 ohms +/- 10% for all signal layers.
8. Emersion gold plating over bare copper
9. All layers minimum trace width/clearence/width = 5/5/5 mils,
10. Trace width can be adusted by matching the impedance requirement by manufacturing
11. All dimensions are in inches unless otherwise noted.

BOARD's DRILL SCHEDULE (Inch)

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Min/Max
○	.01	182	YES	---
⊞	.015	8	YES	---
⊕	.035	40	YES	---
⊞	.041	2	YES	---
⊖	.048	23	YES	---
⊞	.13779528	4	YES	---

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SCHM# B2886
 SPEC# B2887
 ASSM# B2888

UNIVERSITY OF CHICAGO
 ELECTRONICS DEVELOPMENT GROUP

TITLE
 B2887 Specification

SHEET 1 OF 1
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 DRAWN TANG

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 REV 1.0